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(54) **INTEGRATED PASSIVE DEVICES (IPD)  
HAVING A BASEBAND DAMPING RESISTOR  
FOR RADIOFREQUENCY POWER DEVICES  
AND DEVICES AND PROCESSES  
IMPLEMENTING THE SAME**

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**ABSTRACT**

A transistor device includes a metal submount; a transistor die arranged on said metal submount; an IPD component arranged on said metal submount, and the IPD component having a baseband damping resistor arranged on a thermally conductive dielectric substrate; and a second IPD component arranged on said metal submount, and the second IPD component may include a baseband decoupling capacitor arranged on a thermally conductive dielectric substrate.

